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#### /\* WORK EXPERIENCE \*/

#### Shinkawa Ltd., JAPAN

www.shinkawa.com Sep. 2019 – Nov. 2019

# C++ Software Engineer (R&D Department)

- Trained in about Wafer Bump Bonders SBB (operations and UI source code).
- Develop software components for Upgrade UTC run on Windows 10 IOT platform.

### Shinkawa Vietnam Ltd., HCMC

www.shinkawa.com Nov. 2015 – Oct. 2020

### C++ Software Engineer (R&D Department)

- Design and implement new function.
- Research to provide solution and estimation based on customer's requirement.
- Supplementary document for software design, user manual.

## /\* PROJECTS \*/

Wire Bonders (UTC)

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Customer	- Samsung, Hynix SK, UTAC, Orsam, ect.
Description	- UTC software handles wire bonding process.
	- Many UTC machines are controlled by central host via S-Brain and S-Link network.
My responsibilities (features highlight)	- Strip-mapping function of 2D codes using SEMI G84-0303 specification.
	- SimLoop function with automated loop shape optimization.
	- Automatic Bond Level Acquisition function eliminates bond levels setup time after Capillary change.
Technologies used	- C++, MFC framework, SECS, SQL, Visual Studio 2012, internal HOST emulator.
	- IBM Lotus Note and Visual SourceSafe for source control.

#### **Bump Bonders (SBB)**

Description	- UTC software handles bump bonding process (based on UTC software).
My responsibilities (features highlight)	- Develop function to enable the Operator to run production with Wafers whose 2D codes have been
	read with a handheld barcode reader.

# **CAD Data Making Tool (for UTC)**

Description	- Running on AutoCAD. Allowing the bond coordinate data importable to UTC from CAD drawing.
My responsibilities (features highlight)	- Integration tool for AutoCAD from 2016 to 2020 on both Windows 7/10 64-bit
	(previously only support AutoCAD 2015 and earlier).
Technologies used	- HTML, VB.NET, ArxObject, AutoLisp.

## **Personal Web Server**

Description	- The purpose is to store, selectively share and publish personal data information Link: http://nha.sytes.net
Technologies used	- Raspberry pi 3b+, PHP7, HTML, No-IP Dynamic DNS.

### /\* SKILLS \*/

Technical	- Experience in C++ Object-Oriented Programing, C/C++, MFC Framework.
	- Basic knowledge in Python, PyQt5 design (self-study).
Develop tool	- Experience in compilation, testing and debugging the code using Visual Studio.
	- Familiarly with IBM Lotus Note, Visual SourceSafe, TFS for source control.
	- Can use other tools for develop such Visual code, Qt Creator, Git, make file.
Soft skills	- Good ability in teamwork.
	- Good knowledge problem solving and root cause analysis skills.
	- Ability to self-study new technical.
Language	- Ability to read and write English technical document.

## /\* EDUCATION \*/

**HCMC INDUSTRY AND TRADE COLLEGE**, Sep.2011 – Jul.2014 *Bachelor of Information Technology.* 

# /\* INTERESTS \*/

DIY programing, playing guitar and football.